



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D
<i>* : Required Field</i>			

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2013-01-15
Contact Name *	Refer to "Supplier Comment" section	Contact Title	Refer to "Supplier Comment" section
Contact Phone *	Refer to "Supplier Comment" section	Contact Email *	Refer to "Supplier Comment" section
Authorized Representative *	Emilio Castelli	Representative Title	APG MD CHAMPION
Representative Phone *	Refer to "Supplier Comment" section	Representative Email *	Refer to "Supplier Comment" section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/internet/com/support/online_tech_support.jsp		

Uncertainty Statement

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Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
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Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
SPC56EL70L5CBZY	AAUA*FL62BAG	A	MA1A	2013-01-15
Amount		UoM	Unit type	ST ECOPACK Grade
1315.00		mg	Each	ECOPACK® 2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles	 life.augmented	
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy		
Not Applicable ; if coating is used bright, annealed Tin/Silver/Bismuth		Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
CHP	20x20x1.4	144	flat	
Comment				

Material Composition Declaration						Mfr Item Name	AAUA*FL62BAG					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
die (s)	Other inorganic materials	44.949	mg	supplier	die	Silicon (Si)	7440-21-3		43.279	mg	962847	32912
die (s)				supplier	metallization	Aluminium (Al)	7429-90-5		0.08	mg	1780	61
die (s)				supplier	metallization	Copper (Cu)	7440-50-8		0.71	mg	15796	540
die (s)				supplier	metallization	Tantalum (Ta)	7440-25-7		0.225	mg	5006	171
die (s)				supplier	metallization	Cobalt (Co)	7440-48-4		0.002	mg	44	2
die (s)				supplier	metallization	Titanium (Ti)	7440-32-6		0.008	mg	178	6
die (s)				supplier	metallization	Tungsten (W)	7440-33-7		0.006	mg	133	5
die (s)				supplier	passivation	Silicon Nitride (SiN)	68034-42-4		0.18	mg	4005	137
die (s)				supplier	passivation	Silicon Oxide(SiO2)	7631-86-9		0.459	mg	10212	349
Leadframe	Copper & Its alloys	322.678	mg	supplier	alloy	Copper (Cu)	7440-50-8		304.845	mg	944734	231821
Leadframe				supplier	alloy	Iron (Fe)	7439-89-6		7.17	mg	22220	5452
Leadframe				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.432	mg	1339	329
Leadframe				supplier	alloy	Zinc (Zn)	7440-66-6		0.375	mg	1162	285
Leadframe				supplier	tape	poly(4,4'-oxydiphenylene-pyromellitimide)	25036-53-7		7.778	mg	24105	5915
Leadframe				supplier	metallization	Silver (Ag)	7440-22-4		2.078	mg	6440	1580
Die attach		8.245	mg	supplier	glue or tape	Silver (Ag)	7440-22-4		6.493	mg	787508	4938
Die attach				supplier	glue or tape	Urethane acrylate oligomer	na		0.577	mg	69982	439
Die attach				supplier	glue or tape	Methacrylate	na		0.577	mg	69982	439
Die attach				supplier	glue or tape	Acrylate	na		0.577	mg	69982	439
Die attach				supplier	glue or tape	NMP	872-50-4		0.021	mg	2547	16
Bonding wire		2.233		supplier	wire	Gold (Au)	7440-57-5		2.211	mg	990148	1681
Bonding wire				supplier	wire	Palladium (Pd)	7440-05-3		0.022	mg	9852	17
encapsulation		935.876	mg	supplier	mold compound	Solid Epoxy Resin	na		74.87	mg	80000	56935
encapsulation				supplier	mold compound	Phenol Resin	na		37.435	mg	40000	28468
encapsulation				supplier	mold compound	Silica, vitreous	60676-86-0		815.148	mg	871000	619884
encapsulation				supplier	mold compound	Carbon-black	1333-86-4		4.679	mg	5000	3558
encapsulation				JIG Table B	mold compound	Bismuth (Bi)	7440-69-9		3.744	mg	4001	2847
connections coating	Solder	1.019	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		1.019	mg	1000000	775